

Measurement of: Dicing of substrates/Wafers

Equipment: DICING SAW

Property Measured: Cutting/dicing of substrates/wafers in mm scale

Photograph (small size)



Basic Principle:

The cutting machine has a spindle motor and three step motors. A diamond wheel attached to spindle motor is used to cut materials. The blade thickness is about 350 micron. The wafers will be mounted using wax and cooled by flowing water during cutting. The machine is computer controlled.

Capabilities:

Wafers/substrates up to 8 cm x 8 cm can be cut into pieces in mm scale. The cutting rate depends on the hardness of the materials to be cut.

Sample Requirement: Substrates/wafers upto 8 cm x 8 cm